

**LINEAR TECHNOLOGY MATERIALS DECLARATION**

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(Engineering Calculation)

DFN 5mm X 4mm Exp. Pad

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**TOTAL MASS (g) : 0.055007**

COMPONENT MATERIAL	VENDOR/ INDUSTRY NAMES	CONSTITUENT NAME	CAS NUMBER	CONSTITUENT MASS (g)	CONSTITUENT (PPM) OF MATERIAL	CONSTITUENT (PPM) OF TOTAL PKG.		
Active Device	Linear Technology	Silicon (Si)	7440-21-3	0.003693	1000000	67137.234375		
Die Coat	Dow Corning	Silicone	69430-27-9	0.000000	0	0		
Lead Frame	Cu	Copper (Cu)	7440-50-8	0.023117	975000	420257.625		
		Iron (Fe)	7439-89-6	0.000569	24000	10344.1884766		
		Phosphorus (P)	7723-14-0	0.000001	29.9999904633	18.1795921326		
		Zinc (Zn)	7440-66-6	0.000017	700	309.053070068		
		Nickel (Ni)	7440-02-0	0.000000	0	0		
		Silicon (Si)	7440-21-3	0.000000	0	0		
		Magnesium (Mg)	7439-95-4	0.000000	0	0		
		Tin (Sn)	7440-31-5	0.000000	0	0		
<b>Lead Frame Total:</b>				<b>0.023704</b>	<b>999730</b>	<b>430929.03125</b>		
Plating	PMI	Exter. Plating Pb	7439-92-1	0.000000	0	0		
		Exter. Plating Sn	7440-31-5	0.001124	1000000	20429.0058594		
		<b>External Plating Total:</b>				<b>0.001124</b>	<b>1000000</b>	<b>20429.0058594</b>
		Inter. Plating Ni	7440-02-0	0.000000	0	0		
		Inter. Plating Ag	7440-22-4	0.000522	1000000	9489.74804688		
<b>Internal Plating Total:</b>				<b>0.000522</b>	<b>1000000</b>	<b>9489.74804688</b>		
Die Attach	ELECTRICALLY CONDUCTIVE ADHESIVE	Silver (Ag)	7440-22-4	0.001438	750000	26142.2519531		
		Tin (Sn)	7440-31-5	0.000000	0	0		
		Lead (Pb)	7439-92-1	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.000000	0	0		
		Indium (In)	7440-74-6	0.000000	0	0		
		Metal Oxide		0.000000	0	0		
		Antimony (Sb)	7440-36-0	0.000000	0	0		
		Resin (EP)		0.000479	250000	8708.02441406		
<b>Die Attach Total:</b>				<b>0.001917</b>	<b>1000000</b>	<b>34850.2773438</b>		
Encapsulation	MULTI-AROMATIC RESIN Br/Sb FREE	Resin (EP)		0.003117	130000	56665.7890625		
		Bromine (Br)	40039-93-8	0.000000	0	0		
		Silica (SiO2)	60676-86-0	0.020623	860000	374917.75		
		Antimony Trioxide (Sb2O3)	1309-64-4	0.000000	0	0		
		Metal Hydroxide		0.000000	0	0		
		Carbon Black (C)	1333-86-4	0.000240	10000	4363.10205078		
		<b>Encapsulation Total:</b>				<b>0.023980</b>	<b>1000000</b>	<b>435946.625</b>
Bond Wire Estimated	AFW/TANAKA/ Kn	Gold (Au)	7440-57-5	0.000067	1000000	1218.03271484		
					<b>TOTAL MASS (g) :</b>	<b>0.055007</b>		